**ASSIGNMI** 12-23-1998 **˜HEET** *Patents Only*

100927783

To the Honorable Commissioner of Patents ar

~MRD 12-3-98

Please record the attached original documents or copy ...

December 3, 1998
Attorney Dkt: 5649-651

1. Name of conveying party(ies):

Byoung-Taek Lee

Additional name(s) of conveying party(ies) attached? ___ Yes X No

2. Name and address of receiving party(ies):

Samsung Electronics Co., Ltd.
416 Maetan-dong, Paldal-gu
Suwon-City, Kyungki-do
Republic of Korea

JC135 U.S. PTO
09/204596
12/03/98

Additional name(s) & address(es) attached? ___ Yes X No

3. Nature of conveyance:

X Assignment
___ Merger
___ Security Agreement
___ Change of Name
___ Other ______________________

Execution Date: November 28, 1998

4. Application Serial No. ____________ Patent No. ______________

If this document is being filed together with a new application, the execution date of the application is: November 28, 1998

Additional numbers attached? ___ Yes X No

5. Name and address of party to whom correspondence concerning document should be mailed:

**Grant J. Scott**
**Myers Bigel Sibley & Sajovec**
**P.O. Box 37428**
**Raleigh, North Carolina 27627**

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41) $ 40.00

X Enclosed
___ Authorized to be charged to deposit account

8. Deposit account number: **50-0220**

(Attach duplicate copy of this page if paying by deposit account)

DO NOT USE THIS SPACE

9. Statement and signature

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Grant J. Scott, #36,925 ______________ 12/3/98
Signature Date

Total number of pages including cover sheet, attachments and document: 3

Attorney Docket 5649-651

# ASSIGNMENT

THIS ASSIGNMENT, made by me, Byoung-Taek Lee, citizen of the Republic of Korea, residing at 101-1105, Hyundae Kwanak Apt., 1000, Bongcheon-dong, Kwanak-ku, Seoul, Republic of Korea;

WITNESSETH: That,

WHEREAS, I am the sole inventor of certain new and useful improvements in **INTEGRATED CIRCUIT CAPACITORS HAVING RECESSED OXIDATION BARRIER SPACERS AND METHODS OF FORMING SAME**, for which an application for United States Letters Patent has been filed, or is being filed concurrently, in the United States Patent and Trademark Office. I hereby authorize and request Myers Bigel Sibley & Sajovec, P.A., to insert here in parentheses (Application No. _________________, filed _______________________) the filing date and application number of said application when known or to file this Assignment concurrently with the application, and

WHEREAS, Samsung Electronics Co., Ltd., a Korean corporation having a principal place of business at 416 Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea, hereinafter referred to as assignee, is desirous of acquiring the entire right, title and interest in and to said invention as described in said application, and in and to any and all Letters Patent which shall be granted therefor in the United States of America and all foreign countries;

NOW, THEREFORE, To Whom It May Concern, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I have sold and by these presents do hereby sell, assign, transfer and convey unto the said assignee, its successors and assigns, the entire right, title and interest in and to the said invention and application, and in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues thereof which may be granted therefor or thereon, for the full end of the term for which said Letters Patent may be granted, together with the right to claim the priority of said application in all foreign countries in accordance with the International Convention, the same to be held and enjoyed by said assignee, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if this assignment and sale had not been made.

I hereby request that said Letters Patent be issued in accordance with this assignment.

I further covenant and agree that, at the time of the execution and delivery of these presents, I possess full title to the invention and application above-mentioned, and that I have the unencumbered right and authority to make this assignment.

I further covenant and agree to bind my heirs, legal representatives and assigns, promptly to communicate to said assignee or its representatives any facts known to me relating to said invention, to testify in any interference or legal proceedings involving said invention, to execute any additional papers which may be requested to confirm the right of the assignee, its representatives, successors or assigns to secure patent or similar protection for the said invention in all countries and to vest in the assignee complete title to the said invention and Letters Patent, without further compensation, but at the expense of said assignee, its successors, assigns and other legal representatives.

IN WITNESS WHEREOF, I have hereunto set my hand and seal on this 28 day of Nov, 1998.

Byoung Taek Lee (SEAL)
Byoung-Taek Lee

Witnessed by:

[illegible] Young [illegible]

Date: Nov 28, 1998

Hideki Horii

Date: Nov 28, 1998